

## Electrostatic Discharged Protection Devices (ESD) Data Sheet

### Description

UBQ10A05L04HI is a ultra low capacitance TVS array designed to protect high speed data interfaces. It has been specifically designed to protect sensitive components which are connected to high-speed data and transmission lines from over-voltage caused by electrostatic discharge (ESD), cable discharge events (CDE), and electrical fast transients (EFT). It has a typical capacitance of only 0.3pF between I/O pins. This allows it to be used on circuits operating in excess of 3GHz without signal attenuation. It may be used to meet the ESD immunity requirements of IEC61000-4-2. It is designed for easy PCB layout by allowing the traces to run straight through the device. The combination of small size, low capacitance, and high level of ESD protection makes them a flexible solution for applications such as HDMI, UDI, Display Port™, MDDI, Serial ATA and Infiniband circuits.



Contact : ±20kV  
Air : ±20kV

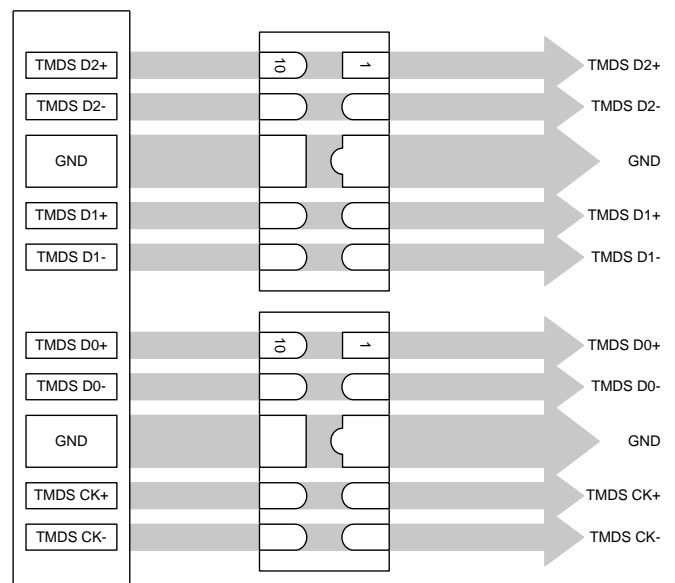
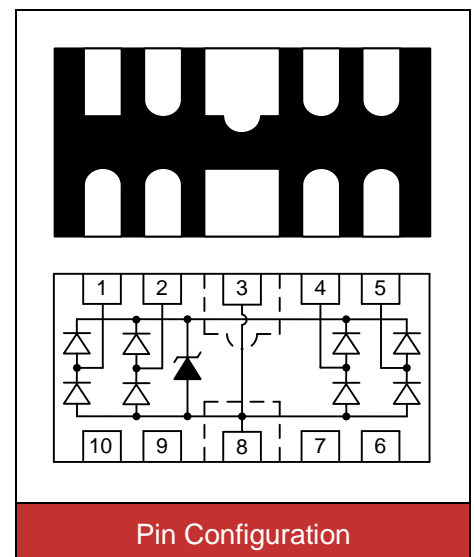


### Features

- IEC61000-4-2 ESD 20kV Air, 20kV contact compliance
- QFN-10 (2.5×1.0×0.5mm) surface mount package
- Protects four I/O lines
- Working voltage: 5V
- Low leakage current
- Low operating and clamping voltages
- Solid-state silicon avalanche technology
- Lead Free/RoHS compliant
- Solder reflow temperature: Pure Tin-Sn, 260~270°C
- Flammability rating UL 94V-0
- Meets MSL level 1, per J-STD-020
- Marking: B 54

### Applications

- High Definition Multimedia Interface (HDMI 1.4)
- Digital Visual Interface (DVI)
- Unified Display Interface (UDI)
- Display Port Interface
- MDDI Ports
- PCI Express
- Serial ATA



## Maximum Ratings

Rating	Symbol	Value	Unit
ESD voltage (Contact discharge)	$V_{ESD}$	$\pm 20$	kV
ESD voltage (Air discharge)		$\pm 20$	
Storage & operating temperature range	$T_{STG}, T_J$	-55~+150	°C

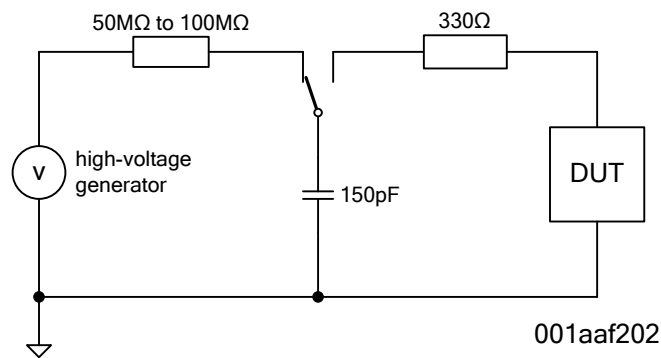
## Electrical Characteristics ( $T_J=25^\circ\text{C}$ )

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Reverse stand-off voltage	$V_{RWM}$				5	V
Reverse breakdown voltage	$V_{BR}$	$I_{BR}=1\text{mA}$	6			V
Reverse leakage current	$I_R$	$V_R=5\text{V}$ Each I/O pin			1	$\mu\text{A}$
Clamping voltage ( $t_p=8/20\mu\text{s}$ )	$V_C$	$I_{PP}=1\text{A}$			9.8	V
Clamping voltage ( $t_p=8/20\mu\text{s}$ )	$V_C$	$I_{PP}=4\text{A}$			15	V
Peak Pulse Current ( $t_p=8/20\mu\text{s}$ )	$I_{PP}$				5	A
Off state junction capacitance	$C_J$	0Vdc, f=1MHz I/O pin to GND		0.6		pF
		0Vdc, f=1MHz Between I/O pins		0.3		pF

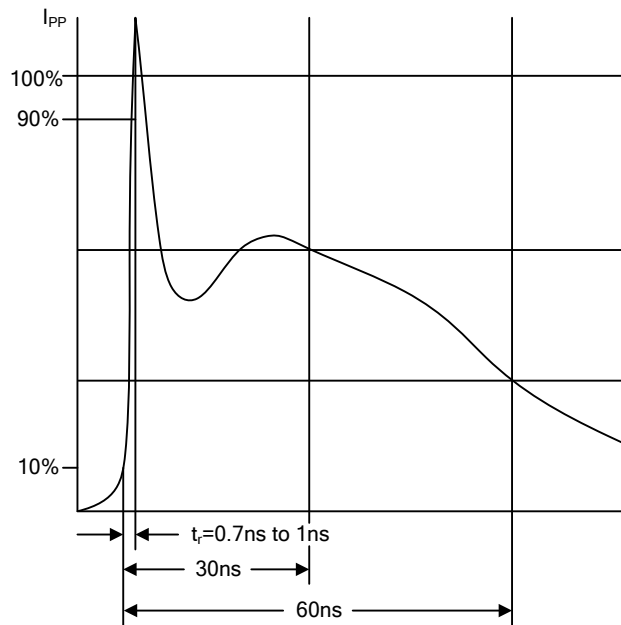
## ESD Protection Standards

### IEC61000-4-2

Interfaces of consumer electronic equipment are widely specified according to the International Electrotechnical Commission standard IEC61000-4-2. This standard is not targeted towards particular devices but towards general equipment, systems and subsystems that may be involved in electrostatic discharge. consists of a 150pF capacitor and a 330Ω series resistor representing the counterpart to the Device Under Test (DUT).



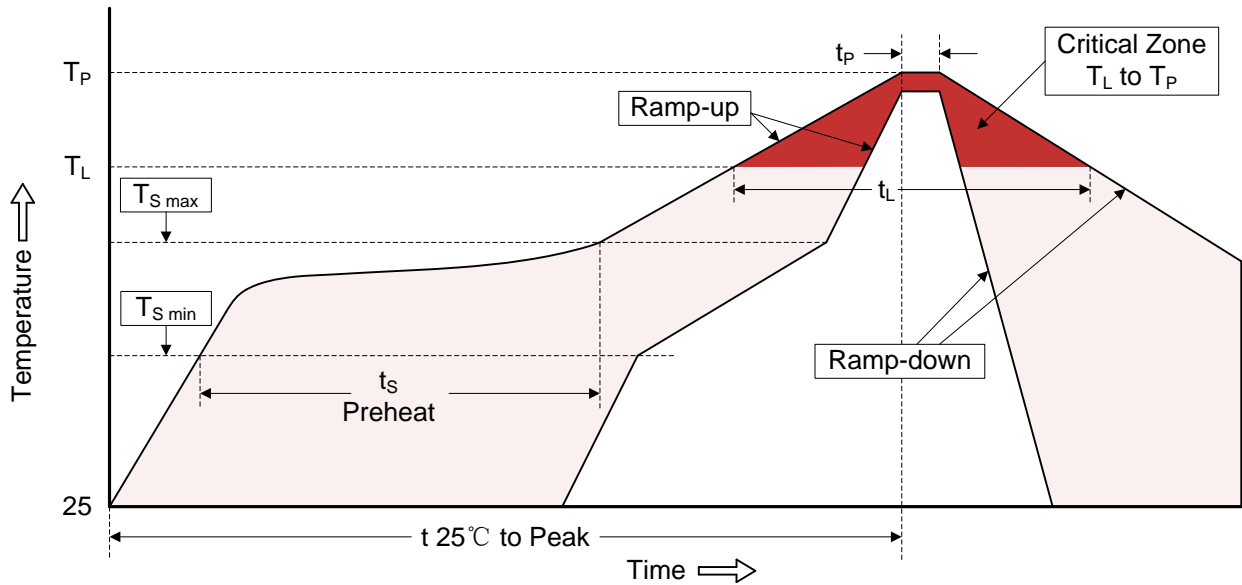
Test circuit according IEC61000-4-2



ESD surge according IEC61000-4-2

**Recommended Soldering Conditions**

Reflow Soldering



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate ( $T_L$ to $T_P$ )	3°C/second max.
Preheat -Temperature Min ( $T_{S\ min}$ ) -Temperature Max ( $T_{S\ max}$ ) -Time (min to max) ( $t_s$ )	150°C 200°C 60-180 seconds
$T_{S\ max}$ to $T_L$ -Ramp-up Rate	3°C/second max.
Time maintained above: -Temperature ( $T_L$ ) -Time ( $t_L$ )	217°C 60-150 seconds
Peak Temperature ( $T_P$ )	260°C
Time within 5°C of actual Peak Temperature ( $t_P$ )	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

**Dimensions (QFN-10)**

	Dimension					
	Millimeters			Inches		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	0.45	0.55	0.65	0.018	0.022	0.026
A1	-	0.03	0.05	-	0.001	0.002
A2	0.13REF			0.005REF		
b1	0.15	0.20	0.25	0.006	0.008	0.010
b2	0.35	0.40	0.45	0.014	0.016	0.018
D	2.40	2.50	2.60	0.094	0.098	0.102
E	0.90	1.00	1.10	0.035	0.039	0.043
e	0.50BSC			0.020BSC		
L	0.30	0.38	0.43	0.012	0.015	0.017

Recommended Soldering Pad Layout

**Packaging**

<p><b>Tape</b></p>	Symbol	Dimension (mm)
	W	8.00±0.30
	P0	4.00±0.10
	P1	4.00±0.10
	P2	2.00±0.10
	D0	Φ1.55±0.10
	D1	Φ0.80±0.05
	E	1.75±0.10
	F	3.50±0.10
	A	1.22±0.10
	B	2.70±0.10
	K	0.70±0.05
	t	0.25±0.05
<p><b>Reel</b></p>	D	Φ178.0±2.0
	D2	Φ13.0
	W1	9.5
	Quantity: 3000PCS	